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Docket No.: 09450/100K673-US2  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Masahiko Furuno et al.

Application No.: Not Yet Assigned

Art Unit: N/A

Filed: Concurrently Herewith

Examiner: Not Yet Assigned

For: BUMP FORMING METHOD,  
PRESOLDERING TREATMENT METHOD,  
SOLDERING METHOD, BUMP FORMING  
APPARATUS, PRESOLDERING  
TREATMENT DEVICE AND SOLDERING  
APPARATUS-

**FIRST PRELIMINARY AMENDMENT**

MS Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

Prior to examination on the merits, please amend the above-identified U.S. patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 8 of this paper.